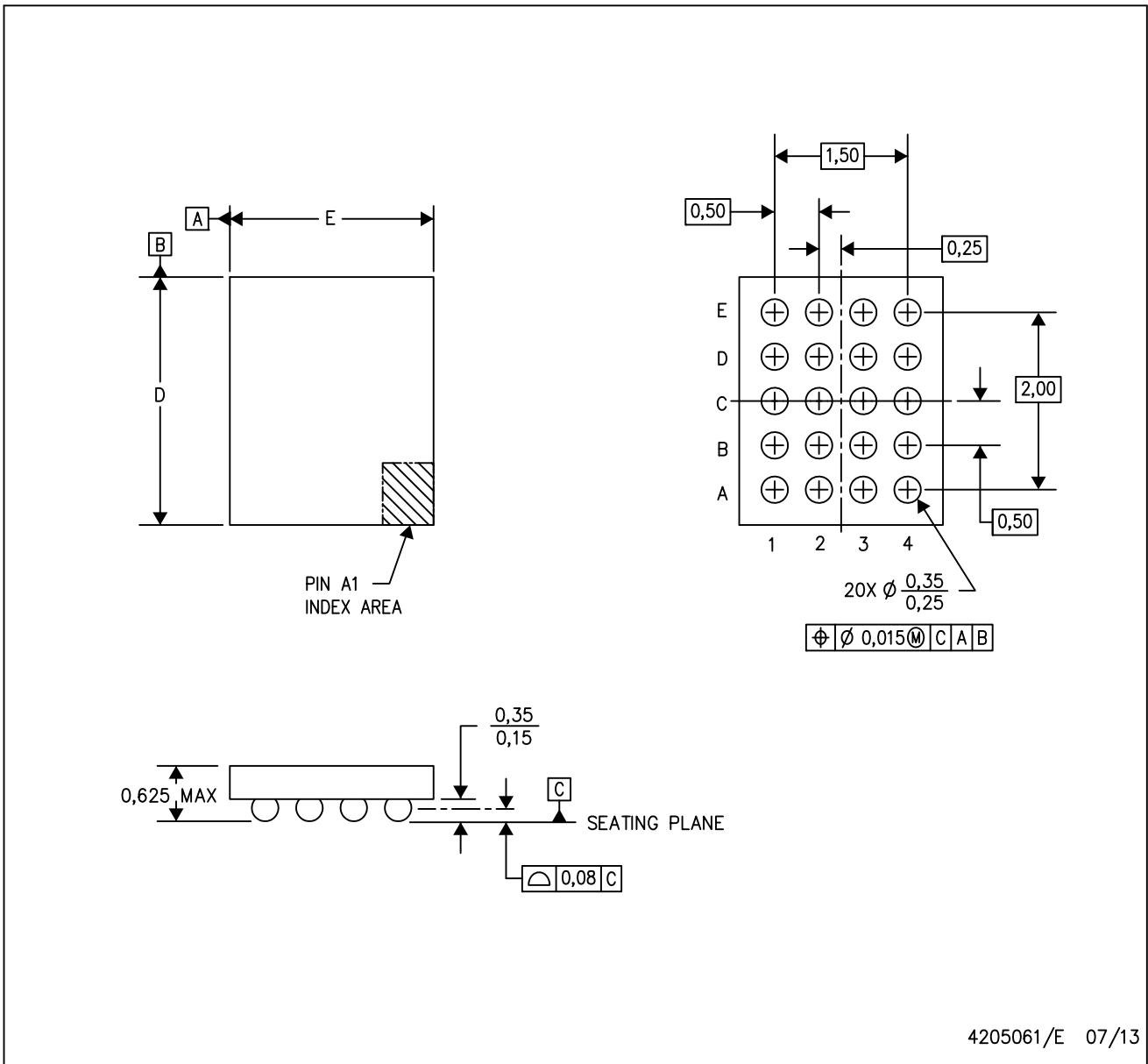


YZJ (R-XBGA-N20)

DIE-SIZE BALL GRID ARRAY



4205061/E 07/13

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

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